

Thick Film Chip Resistors, High Voltage



| STANDARD ELECTRICAL SPECIFICATIONS | | | | | | | |
|------------------------------------|-----------------------------|------------------------|---------------------------------|--|--|--|--|
| MODEL | RESISTANCE (1) (Ω) | POWER RATING (W) | VOLTAGE RATING (V) (max.) | | | | |
| CRHV1206 | 2M - 8G | 0.300 | 1500 | | | | |
| CRHV1210 | 4M - 10G | 0.450 | 1750 | | | | |
| CRHV2010 | 6M - 35G | 0.500 | 2000 | | | | |
| CRHV2510 | 10M - 40G | 0.600 | 2500 | | | | |
| CRHV2512 | 12M - 50G | 0.700 | 3000 | | | | |

Notes

- $^{(1)}$ Resistance values below 1 G Ω are calibrated at 100 V $_{DC}$, and values of 1 G Ω and above are calibrated at 1000 V $_{DC}$. Calibration at other voltages available upon request.
- For non-standard sizes, lower values or higher power rating requirement, contact factory

ELECTRICAL SPECIFICATIONS

(Reference only: Not for all values specified. Consult factory for your size and value.)

Resistance Range: 2 M Ω to 50 G Ω

Resistance Tolerance: \pm 1 %, \pm 2 %, \pm 5 %, \pm 10 %, \pm 20 % Temperature Coefficient: \pm 100 ppm/°C (- 55 °C to + 150 °C)

Voltage Rating: 1500 V - 3000 V

Short Time Overload: Less than 0.5 % AR

FEATURES

- High voltage up to 3000 V
- Outstanding stability < 0.5 %
- Flow solderable
- Custom sizes available
- Automatic placement capability
- Available with either wraparound terminations or as a single termination flip chip
- Tape and reel packaging available
- Internationally standardized sizes
- Suitable for solderable, epoxy bondable, or wire bondable applications
- Termination: Gold, palladium silver, platinum gold, platinum silver, platinum palladium gold or solder-coated nickel barrier available
- Multiple styles, termination materials and configurations, allow wide design flexibility
- Non-magnetic terminations available
- Lead (Pb)-free version is RoHS compliant

MECHANICAL SPECIFICATIONS

Construction: 96 % alumina substrate with proprietary cermet resistance element and specified termination material

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature: - 55 °C to + 150 °C

Life: Less than 0.5 % change when tested at full rated power (Reference only: Not for all values specified. Consult factory for your size and value.)

| VOLTAGE COEFFICIENT OF RESISTANCE CHART | | | | | |
|---|-------------|-------------|-----------------------------------|--|--|
| SIZE | VALUE (Ω) | VCR (ppm/V) | FURTHER INSTRUCTIONS | | |
| CRHV1206 | 2M to 199M | 25 | Values over 200M, consult factory | | |
| CRHV1210 | 4M to 200M | 25 | Values over 200M, consult factory | | |
| CRHV2010 | 6M to 99M | 15 | Values over 1G, consult factory | | |
| | 100M to 1G | 20 | | | |
| CRHV2510 | 10M to 99M | 10 | Values over 1G, consult factory | | |
| | 100M to 1G | 15 | | | |
| CRHV2512 | 12M to 999M | 10 | Values over 5G, consult factory | | |
| | 1G to 5G | 25 | | | |

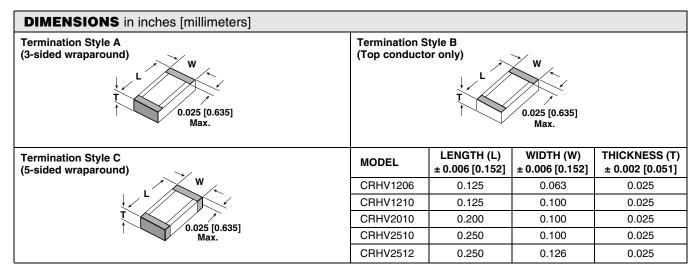
GLOBAL PART NUMBER INFORMATION New Global Part Numbering: CRHV1206AF100MFKFB (preferred part number format) Α 0 М В GLOBAL TERM RESISTANCE SOLDER SIZE **TERM MATERIAL** TOLERANCE **TCR PACKAGING** MODEL **TERMINATION** STYLE VALUE **K** = 100 ppm **CRHV** 1206 A = 3-sided A = Palladium silver M = Million $F = \pm 1.0 \%$ **E** = Sn100 **B** = Bulk **N** = 200 ppm $\mathbf{F} = \frac{\text{Sn}95}{\text{Ag5}}$ **B** = Platinum gold 1210 G = Billion $\mathbf{B} = \text{top only}$ $G = \pm 2.0 \%$ T = Tape and $4M70 = 4.7 M\Omega$ $\mathbf{W} = 350 \text{ ppm}$ 2010 $\mathbf{C} = Gold$ $J = \pm 5.0 \%$ N = No solder C = 5-sided reel 2510 = Platinum silver W = Waffle 10M0 = 10 MO $K = \pm 10.0 \%$ **P**= 500 ppmSn62/Pb36/Ag2 2512 E = Platinum **1G00** = 1 GΩ $M = \pm 20.0 \%$ palladium gold **F** = Nickel barrier T = Sn90/Pb10Historical Part Numbering: CRHV1206AF1006F100e2 (will continue to be accepted) 1006 CRHV 1206 100 e2 HISTORICAL **TERM TERM** RESISTANCE **SOLDER** SIZF. **TOLERANCE** TCR MODEL STYLE **MATERIAL** VALUE **TERMINATION**

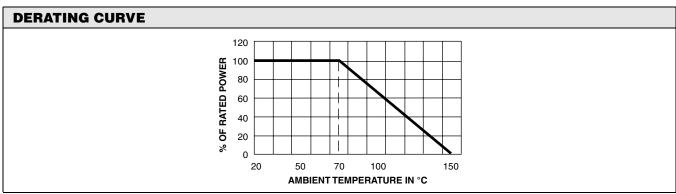
Pb containing terminations are not RoHS compliant, exemptions may apply

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| TYPE | TERMINATION MATERIAL | TERMINATION STYLE | TERMINATION STYLE/ MATERIAL CODE | SOLDER TERMINATION CODE | |
|----------------------------------|---------------------------------|----------------------|-------------------------------------|------------------------------|--|
| Solderable | Nickel barrier | 3-sided (wraparound) | AF | E, F, S, or T ⁽³⁾ | |
| | Nickel balliel | Top only (flip chip) | BF | | |
| Wire bondable/ Solderable | | 3-sided (wraparound) | AE | N, F or S ⁽¹⁾ | |
| | Platinum palladium gold | Top only (flip chip) | BE | | |
| | | 5-sided (wraparound) | CE | | |
| Wire bondable/ Epoxy bondable | | 3-sided (wraparound) | AC | | |
| | Gold | Top only (flip chip) | BC | N | |
| | | 5-sided (wraparound) | CC | | |
| Epoxy bondable | Palladium silver ⁽²⁾ | 3-sided (wraparound) | AA | | |
| | | Top only (flip chip) | BA | | |
| | | 5-sided (wraparound) | CA | | |
| | | 3-sided (wraparound) | AB | | |
| | Platinum gold | Top only (flip chip) | BB | N | |
| | | 5-sided (wraparound) | СВ | | |
| | | 3-sided (wraparound) | AD | | |
| | Platinum silver | Top only (flip chip) | BD | | |
| | | 5-sided (wraparound) | CD | | |

Notes

- (1) Use solder termination N for applications requiring wire bondable mounting, and solder terminations F or S for applications requiring solderable mounting
- (2) While not recommended, palladium silver terminations could be used for solderable applications when using a solder alloy containing silver.
- (3) Standard solder plating for the nickel barrier parts are solder terminations E or T. Hot solder dipped terminations F or S are also available.

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